

## CONTACT

✉ [eddiensamuels@gmail.com](mailto:eddiensamuels@gmail.com)

🌐 [eddiesamuels.com](http://eddiesamuels.com)

## SKILLS

schematic & pcb

board bringup

product dev

3d modeling

soldering

# EDDIE SAMUELS

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## EXPERIENCE

comma.ai 2016 – now

*VP of Hardware*

- hardware development of the eon, panda, & secret projects
- process design & parts sourcing for production of 10k units
- enclosure design with a 3D printed focus
- android/linux kernel support for Qualcomm Snapdragon
- user facing packaging design & production

Lockheed Martin 2015 – 2016

*Associate Electrical Engineer*

- pcb bring up and documentation for test equipment
- development of MATLAB software to search for RF spurs

Lockheed Martin summer 2014

*Electrical Engineer Intern*

- joint program with the New York NASA Space Grant Consortium
- development of underwater rover and corresponding curriculum for STEM outreach program

## EDUCATION

University of Rochester 2011 – 2015

*B.S. in Electrical & Computer Engineering*